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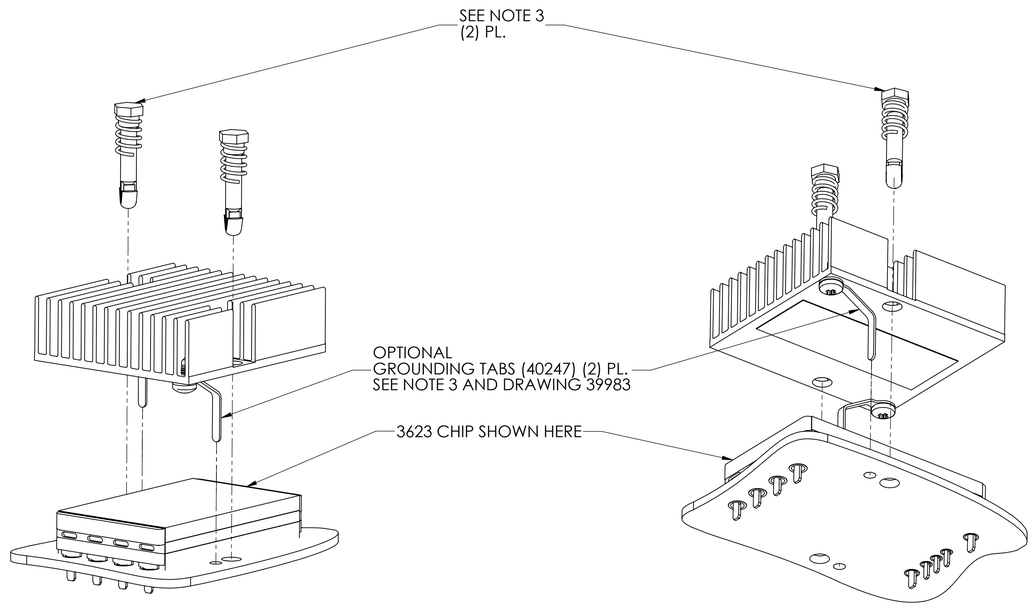
REV.	DESCRIPTION	INTL	DATE	APVD
1	RELEASED PER E140954a	SJW	10/30/14	RH
2	REVISED PER E190393	REJH	07/30/19	RLT
3	REVISED PER E200529	DKT	10/19/20	RLT



ISO ASSY REF ONLY

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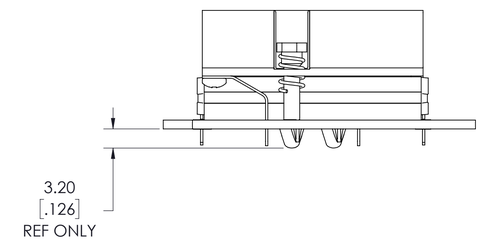
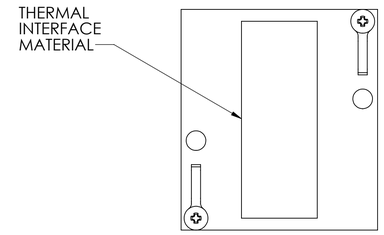
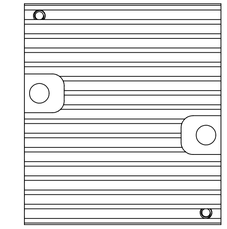
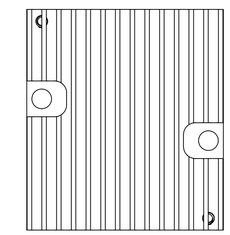




BOTTOM VIEW



X-FLOW (XF)
(HEAT SINK ONLY SHOWN)



LONG-FLOW (LF)
(HEAT SINK ONLY SHOWN)

NOTES:

1. FOR PCB LAYOUT SEE VICOR APPLICATION DRAWING 39983.
2. THE SOLDERING METHOD USED FOR CHIPS (AND OPTIONAL HEATSINK GROUNDING) IS IMPORTANT WHEN SELECTING A THERMAL INTERFACE MATERIAL (TIM). THE PHASE-CHANGE TIM SHOWN IN THESE ILLUSTRATIONS MAY BE DAMAGED BY TEMPERATURES OVER 125C, SO TWO ASSEMBLY PROCEDURES ARE DESCRIBED BELOW:
   (A) FOR HAND-SOLDERING ONLY,
   (B) FOR WAVE-SOLDERING AND/OR HAND-SOLDERING.

   (A) PLACE CHIP AND TOP-SIDE HEATSINK (WITH PRE-ATTACHED TIM AND GROUNDING TABS) ON PCB. WHILE SUPPORTING PCB, INSERT PLASTIC PUSH-PINS THROUGH HEATSINK AND PCB. (SELECT PROPER PUSH-PIN LENGTH FROM TABLE ON THIS DRAWING.) HAND-SOLDER CHIP AND GROUNDING PINS.

   (B) WAVE SOLDERING TEMPERATURES ARE UNSUITABLE FOR PLASTIC PUSH-PINS AND PHASE-CHANGE TIM, SO PARKER CHOMERICS GEL8010 IS RECOMMENDED AS A TIM. APPLY A UNIFORM .003" (.076MM) LAYER OF TIM TO THE TOP SURFACE OF THE CHIP, OR TO THE BOTTOM SURFACE OF THE HEATSINK. PLACE CHIP ON PCB AND TOP-SIDE HEATSINK ON CHIP. WITH A CUSTOM FIXTURE APPLY APPROX. 10 LBS LOAD TO THE TOP-SIDE HEATSINK AND THEN WAVE-SOLDER ALL PINS. REMOVE FIXTURE AND, WHILE SUPPORTING PCB, INSERT PLASTIC PUSH-PINS THROUGH HEATSINK AND PCB. (SELECT PROPER PUSH-PIN LENGTH FROM TABLE ON THIS DRAWING.)
3. CARE SHOULD BE TAKEN TO AVOID FULLY COMPRESSING THE PUSH-PIN SPRING DURING INSTALLATION AS THIS WOULD EXPOSE THE CHIP TO FORCES GREATER THAN THE RECOMMENDED LIMIT OF 3.1 LBF (13.8 N) PER PUSH-PIN.
4. RoHS COMPLIANT PER CST-0001 LATEST REVISION.

PUSH-PIN SELECTION

PUSH-PINS W/ SPRINGS (100/BAG)	COLOR	PCB THK NOMINAL RANGE	PCB THK MINIMUM	PCB THK MAXIMUM
32434	WHITE	1.143 MM TO 1.422 MM [.045"] TO [.056"]	1.016 MM [.040"]	1.575 MM [.062"]
32435	BLACK	1.448 MM TO 2.311 MM [.057"] TO [.091"]	1.295 MM [.051"]	2.565 MM [.101"]
32436	BLUE	2.337 MM TO 3.023 MM [.092"] TO [.119"]	2.083 MM [.082"]	3.353 MM [.132"]
32437	GRAY	3.048 MM TO 3.607 MM [.120"] TO [.142"]	2.743 MM [.108"]	3.988 MM [.157"]

HEATSINK SELECTION

	HEATSINK TYPE	P/N HEATSINK ONLY	P/N HEATSINK W/ TIM ONLY	P/N HEATSINK, TIM AND GROUND TAB	P/N HEATSINK W/GROUND TAB ONLY
SOLDERING METHOD (SEE NOTE 2)	-	2(B) WITH VICOR 40325 THERMAL GEL	2(A) HAND SOLDER ONLY	2(A) HAND SOLDER ONLY	2(B) WITH VICOR 40325 THERMAL GEL
2322	XF 11MM	39966	40488	40138	40478
	LF 11MM	39965	40489	40142	40479
3623	XF 11MM	39968	40490	40139	40480
	LF 11MM	39967	40491	40143	40481

DRAWN BY	DATE	VICOR	SWD
Robert Wasik	7/22/2013	APP DWG, CHIP PUSHPIN TOPSIDE HS, 3623, 2322	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE : INCH / [MM]
TOLERANCES ARE:
DECIMALS X.XX [X.X] = ±0.01 [0.25] ANGLES ±1°
X.XXX [X.XX] = ±0.005 [0.127]

THIRD ANGLE PROJECTION

DO NOT SCALE DRAWING

SIZE	CAGE CODE	DWG NO	REV
D	67131	40112	3

SCALE 2:1 SHEET 1 OF 1